



Electronic Design Innovation Conference

电子设计创新大会

April 1-3, 2019  
China National Convention Center  
Beijing, China

# Advances in Recent PCB Design Verification Flows

Lars Van Der Klooster  
Director of Asia Pacific Operations  
NI, AWR Group

# EM in Microwave Office: Design and Verification Flows

- **Design Flow:** EM is used while making the circuit.
  - Checking a model's accuracy: e.g. – a wide output line on a power amplifier.
  - A model doesn't exist: e.g. – An octagonal spiral inductor.
  - Coupling between parts of the circuit: e.g. – lines coupling to a distributed filter.
  - The completed circuit is sent out to external tools for manufacturing and other layout.
  - MWO has nice technology for this flow: e.g. – Extraction, parameter based layout, shape simplification rules, PDK cells, hierarchical layout.
- **Verification Flow:** A layout is brought into Microwave Office to simulate in EM.
  - Checking a completed layout to see if any signal integrity issues: e.g. – sufficient grounding or radiation.
  - The finished layout might be very complicated: e.g. - multiple power planes, traces.
  - The EM simulator, AXIEM, is setup: e.g. – port type and location.
  - The layout is meshed and simulated.

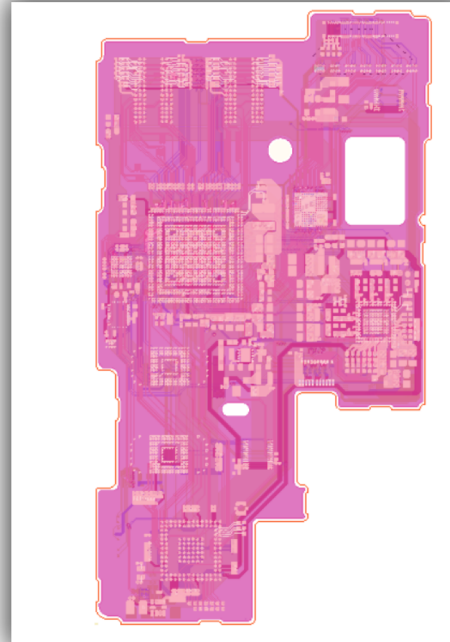
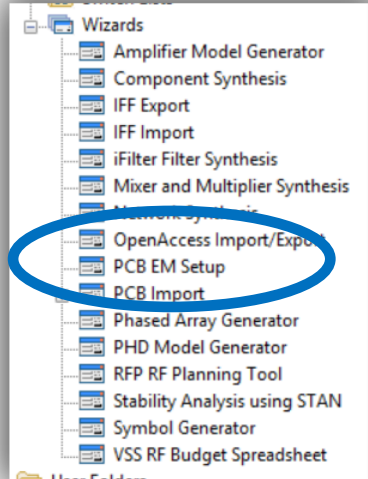
## V14 – EM Verification Flow Requirements

- Must work well for commercially complicated board topologies.
  - Hundreds of nets.
  - Multiple power planes connected by many vias.
  - Dozens of surface mount parts.
- Must work with commercial layout tools.
  - Cadence Allegro, Zuken, Mentor Graphics, Altium.
- Should have knowledge of board stackup, and material properties.
- Ability to select nets and surrounding layout easily.
- Ability to simplify layout as needed to get reasonable mesh.
- Ability to easily have ports added.

# What We Did in V14

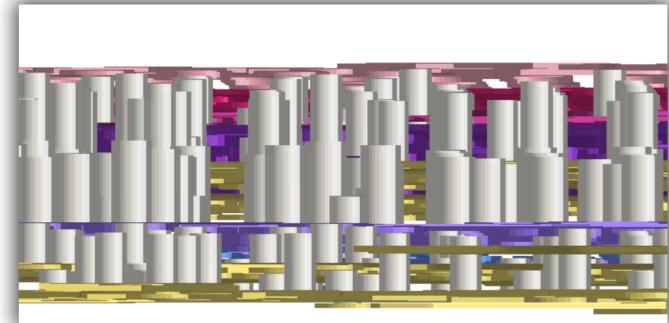
- ODB++ and IPC-2581 layout languages based. (Had some of this V13.)
  - Supported by all commercial tools.
  - Have a lot information besides the layout: nets, materials, and board stackup.
- Imports directly into Microwave Office (V13 – had to go through a third party tool.)
- Controlled with a PCB Import Wizard
  - Tabular display and control of nets, layers, and materials.
  - STACKUP block is automatically created for EM simulation.
- Nets can be identified easily and layout simplified as needed.
- Ports (pin ports) are automatically added at selected nets.
- Net selection understands surface mount part gaps, and more complicated multiple connected parts.
- S-parameter block in schematic has layout-like symbol and appropriate net names.

# An Example – A Board Made in Zuken



Imported Board

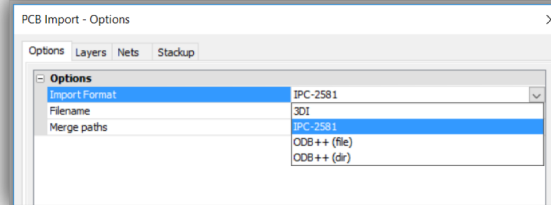
- Imported as IPC 2581
- 11 layer FR4 Board
- 10 conducting layers
- 14 via types



Close-up 3D View of Vias

# The Import Wizard

## Select Import Format



## The Layers Imported

PCB Import - Layers (Showing 83 of 83)

Options	Layers	Nets	Stackup
Import	Name	Type	Negative
<input checked="" type="checkbox"/>	Conductor-1	SIGNAL	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Conductor-2	SIGNAL	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Conductor-3	SIGNAL	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Conductor-4	SIGNAL	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Conductor-5	MIXED	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Conductor-6	MIXED	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Conductor-7	SIGNAL	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Conductor-8	SIGNAL	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Conductor-9	SIGNAL	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Conductor-10	SIGNAL	<input type="checkbox"/>
<input type="checkbox"/>	Symbol-A	SILKSCREEN	<input type="checkbox"/>
<input type="checkbox"/>	Resist-A	SOLDERMASK	<input type="checkbox"/>
<input type="checkbox"/>	MetalMask-A	SOLDERPASTE	<input type="checkbox"/>
<input type="checkbox"/>	HeightLimit-A	GRAPHIC	<input type="checkbox"/>
<input type="checkbox"/>	CompArea-A	GRAPHIC	<input type="checkbox"/>

## Nets Imported

PCB Import - Nets (Showing 489 of 489)

Options	Layers	Nets	Stackup
Import	Net Name		
<input checked="" type="checkbox"/>	BT_UART_CTS		
<input checked="" type="checkbox"/>	EMMC_B_DATA[2]		
<input checked="" type="checkbox"/>	MODE[0]		
<input checked="" type="checkbox"/>	IN_CAM_DATA[1]		
<input checked="" type="checkbox"/>	VFPIO_IP8V		
<input checked="" type="checkbox"/>	LCD_D[15]		
<input checked="" type="checkbox"/>	TX_I2S_WCK[0]		
<input checked="" type="checkbox"/>	EMMC_B_DATA[1]		
<input checked="" type="checkbox"/>	DDR_DQ[4]		
<input checked="" type="checkbox"/>	SIGN013538		
<input checked="" type="checkbox"/>	SIGN013539		
<input checked="" type="checkbox"/>	LCD_D[14]		
<input checked="" type="checkbox"/>	DDR_DQ[10]		
<input checked="" type="checkbox"/>	VAPREF_IO[3]		
<input checked="" type="checkbox"/>	SIGN013541		

## Stackup Creation

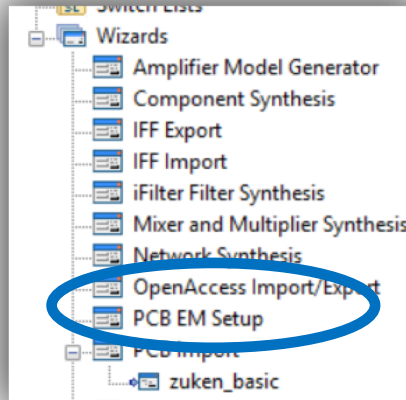
PCB Import - Stackup (Showing 21 of 21)

OptionsLayersNetsStackup

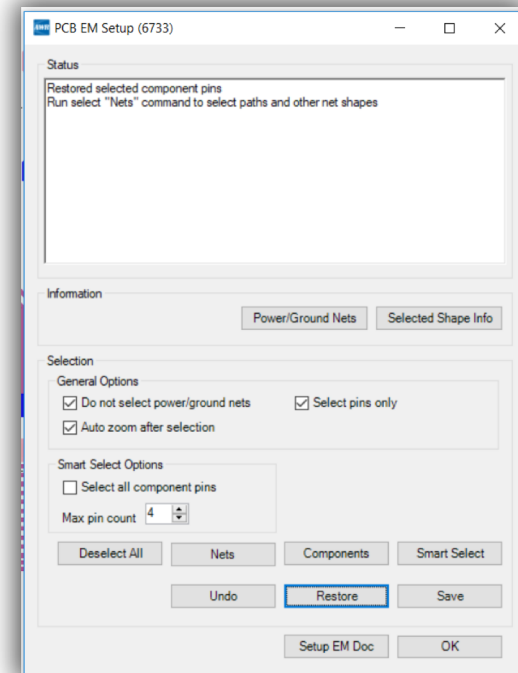
Layer Name	Material	Thickness (mm)	Conductivity (S/m)	Dielectric Constant	Loss Tan
Conductor-1	COPPER	0.02	5.969e+07	1	0
Resist-A	mat1	0.02	0	4.5	0.02
InsulateLayer1-2	ABF	0.075	0	4.5	0.02
Conductor-2	COPPER	0.02	5.969e+07	1	0
InsulateLayer2-3	ABF	0.075	0	4.5	0.02
Conductor-3	COPPER	0.02	5.969e+07	1	0
InsulateLayer3-4	ABF	0.075	0	4.5	0.02
Conductor-4	COPPER	0.04	5.969e+07	1	0
InsulateLayer4-5	FR-4	0.1	0	4.5	0.02
Conductor-5	COPPER	0.018	5.969e+07	1	0
InsulateLayer5-6	FR-4	0.1	0	4.5	0.02
Conductor-6	COPPER	0.018	5.969e+07	1	0
InsulateLayer6-7	FR-4	0.1	0	4.5	0.02
Conductor-7	COPPER	0.04	5.969e+07	1	0
InsulateLayer7-8	ABF	0.075	0	4.5	0.02



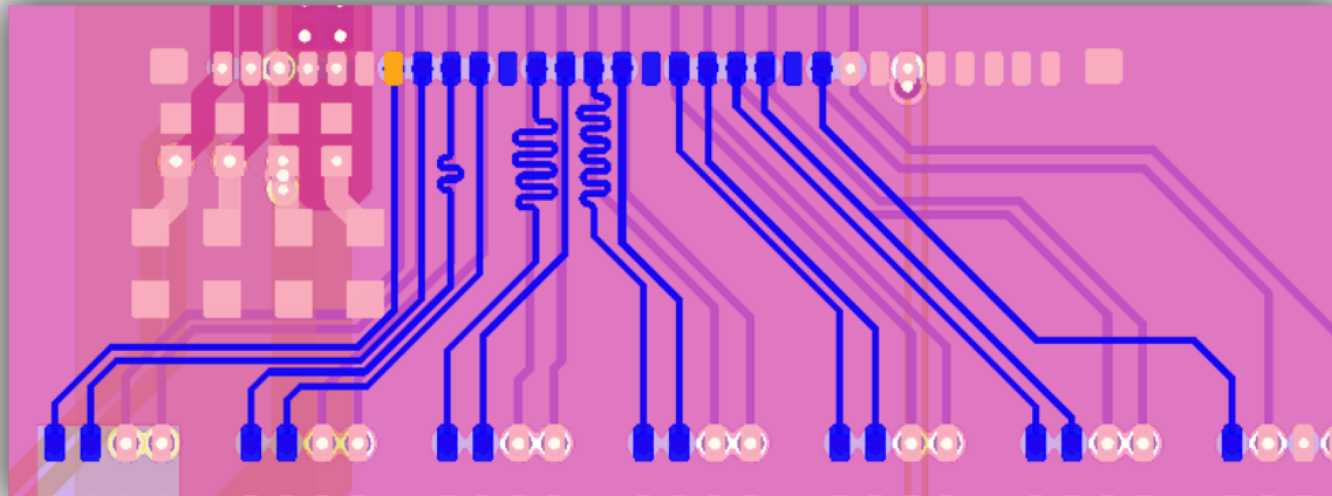
# The EM Setup Wizard



- Normally – we select the pins we want.
- Smart Select – selects net attached to pin.
- Can select other pins on component with Smart Select.
- Can propagate through series component.

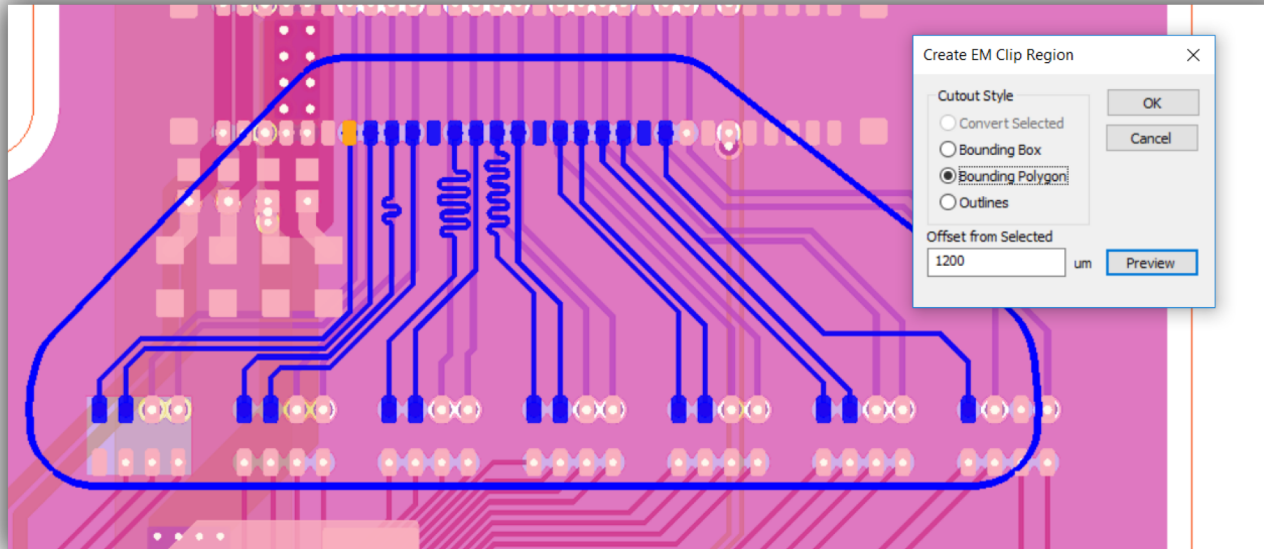


# The Selected Pins and Nets





# Create the Boundary for the Region for EM



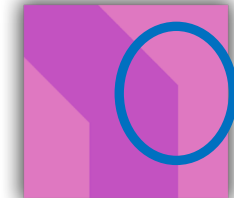
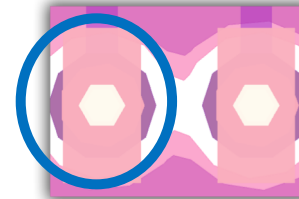
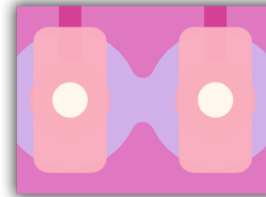
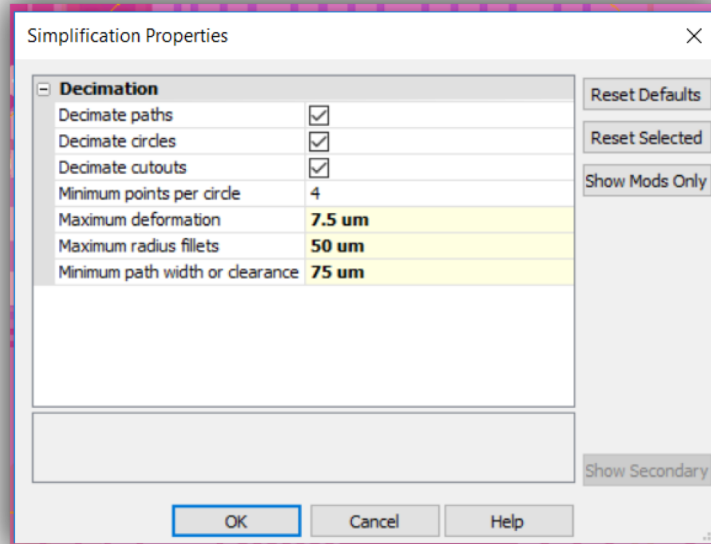
# Shape Simplification

Before

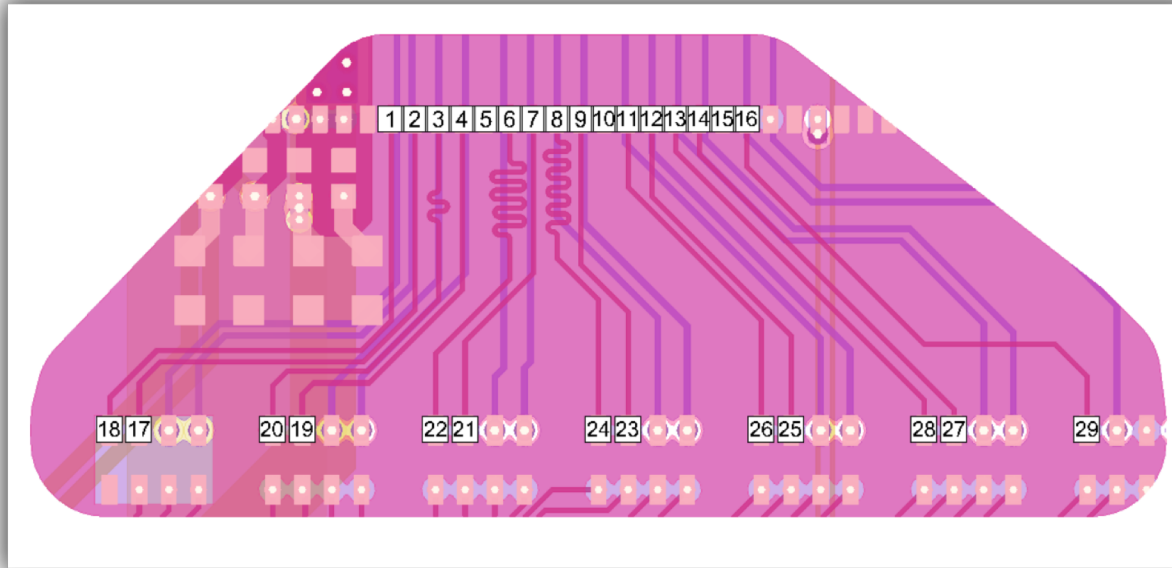
Vias

Bends

After

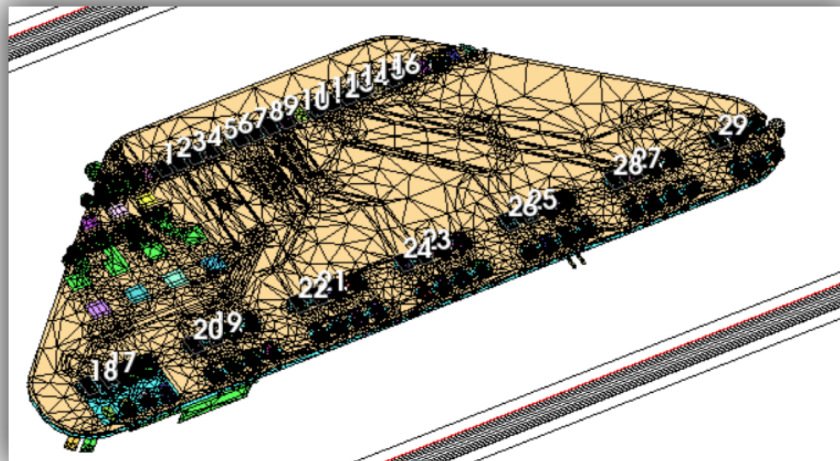


# Ports Have Been Added Automatically



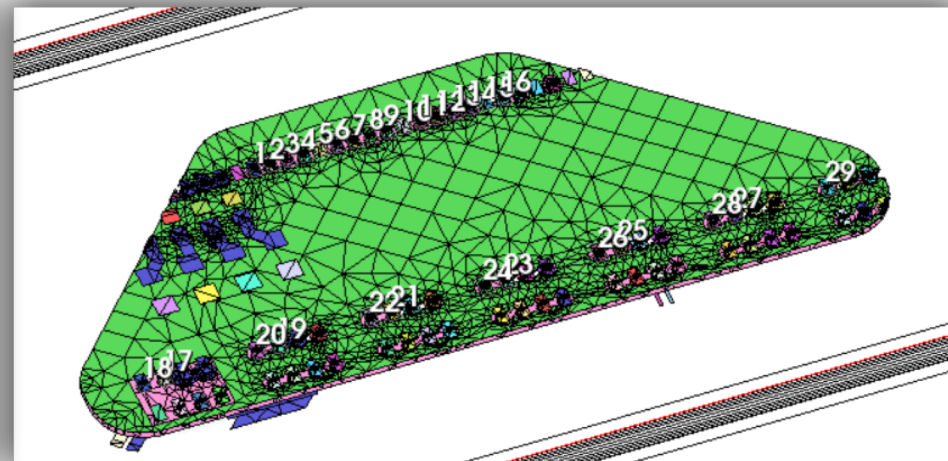
# Improved Meshing in AXIEM

**V13 Mesh**



81K Unknowns

**V14 Mesh**



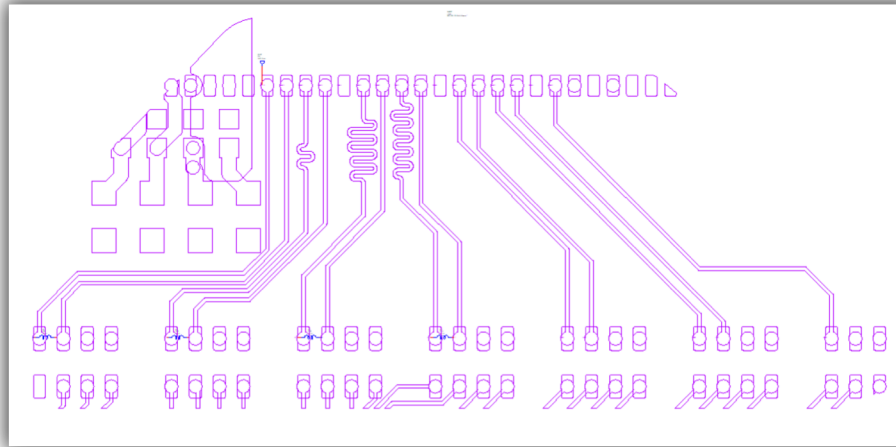
22K Unknowns

## Meshing – Why is it Better

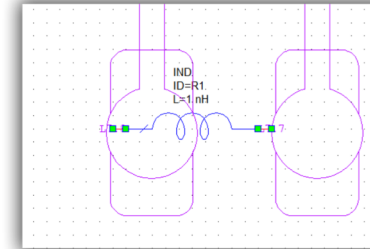
- We have fewer meshes.
  - Faster to simulate
  - Solve time for iterative solver is  $N^{1.6}$ .
- They are more square and equilateral triangles – fewer slivers.
  - Better conditioned matrix – easier to solve iteratively.
- We don't mirror the mesh through planes.
- Shape simplification reduced rounded corners and circular vias.
- ... and – we spent a lot of time working on mesh algorithms!



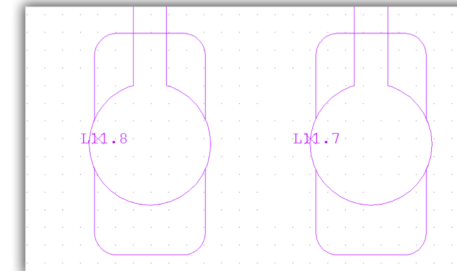
# S-parameters Used in a Schematic



The sub-circuit block looks like the layout.



Easy to place elements.



The pin names are in the symbol.



# Conclusions

- V14 has improved layout import for verification flow.
- It directly can read ODB++ and IPC-2581 layout files.
  - Layers, materials, pins and nets are included.
- It is controlled by a new PCB Import Wizard.
- A new EM Setup Wizard allows:
  - Selection of the desired pins and nets.
  - Creates a cutout region of the layout automatically.
  - Simplifies bends and vias.
- AXIEM has been improved:
  - Pin ports are automatically added without manual placement.
  - Meshing has been improved for board layout geometries.